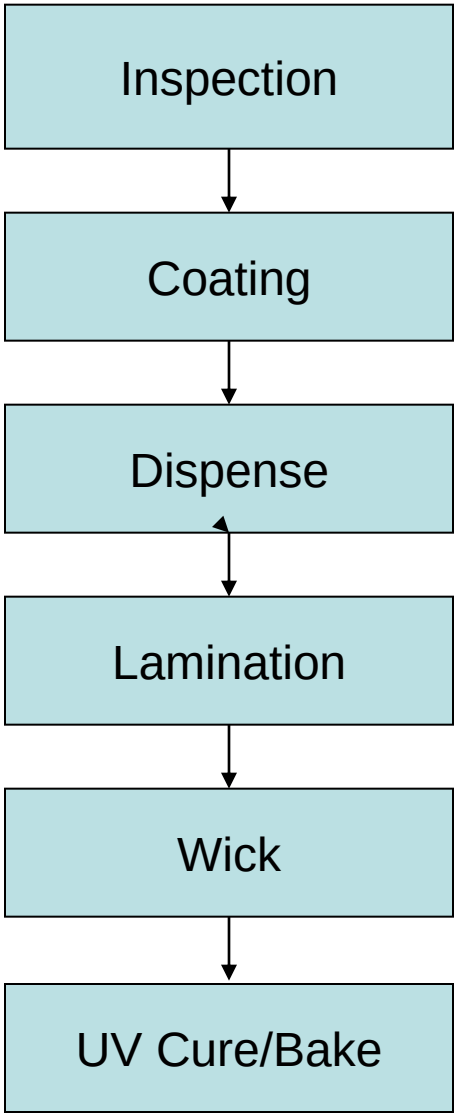
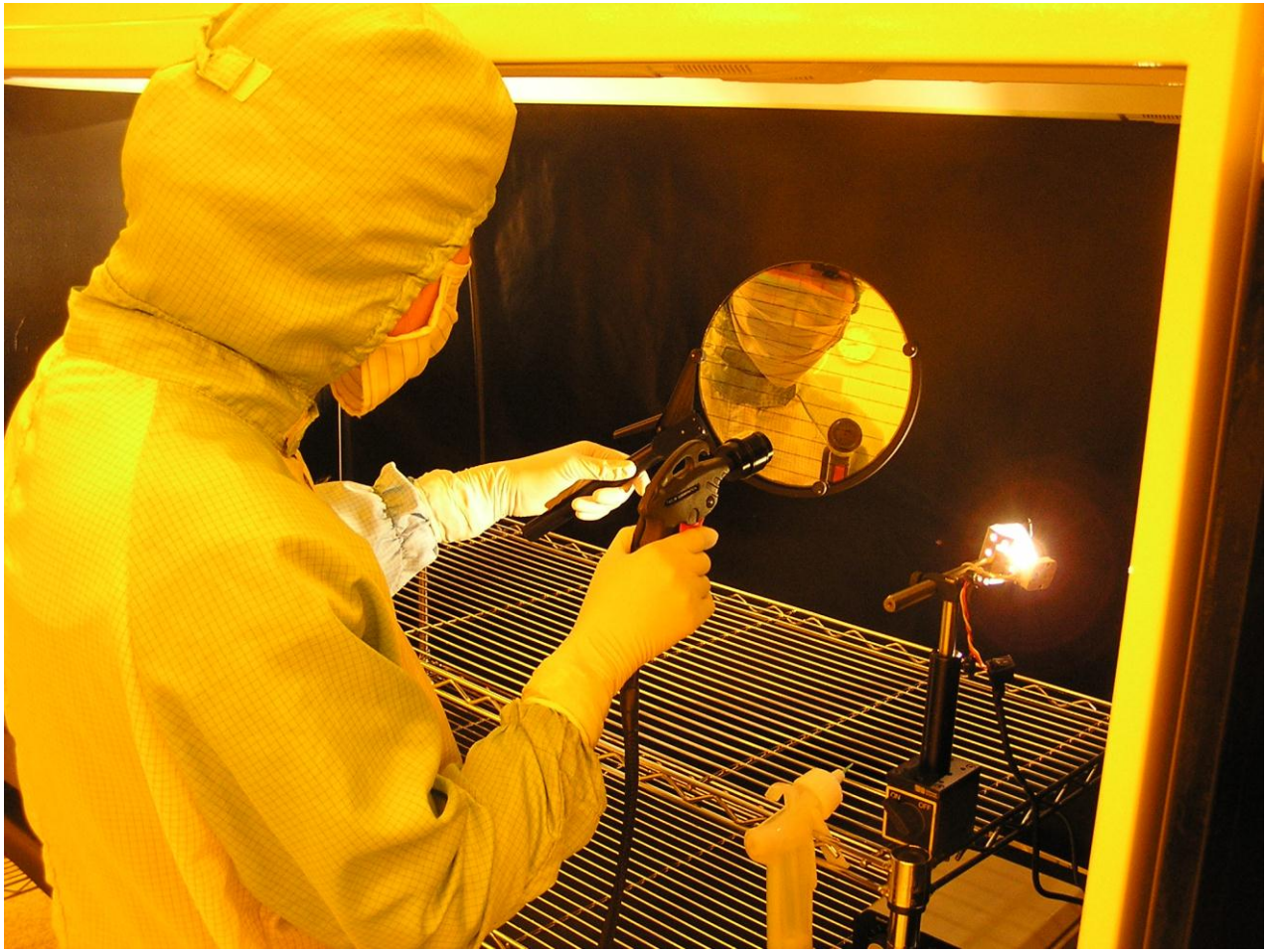
SpatiaLight Korea Manufacturing

May 2006

Laminate Fabrication



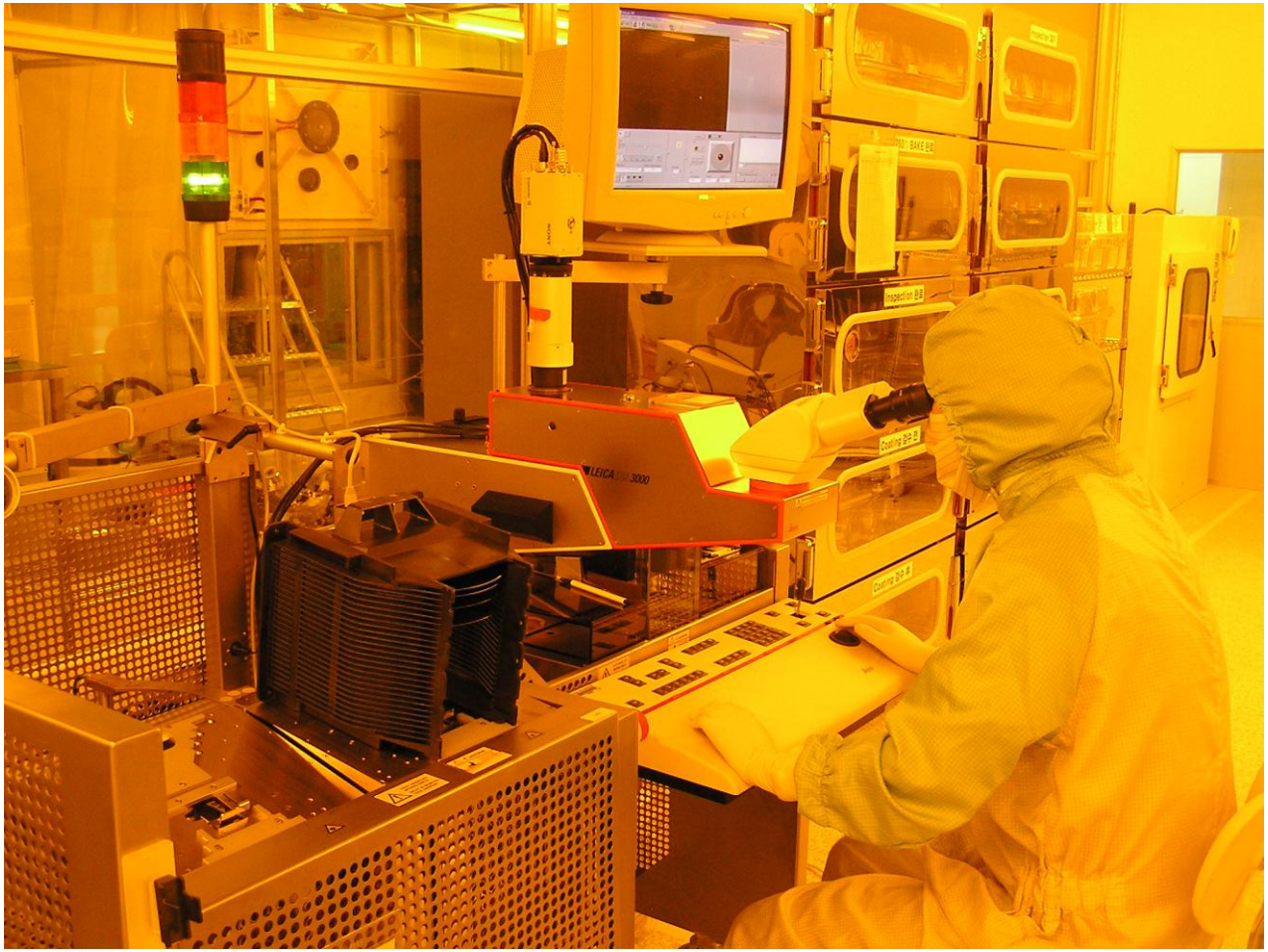
Visual Wafer Inspection



KLA-Tencor Wafer Laser Scanner



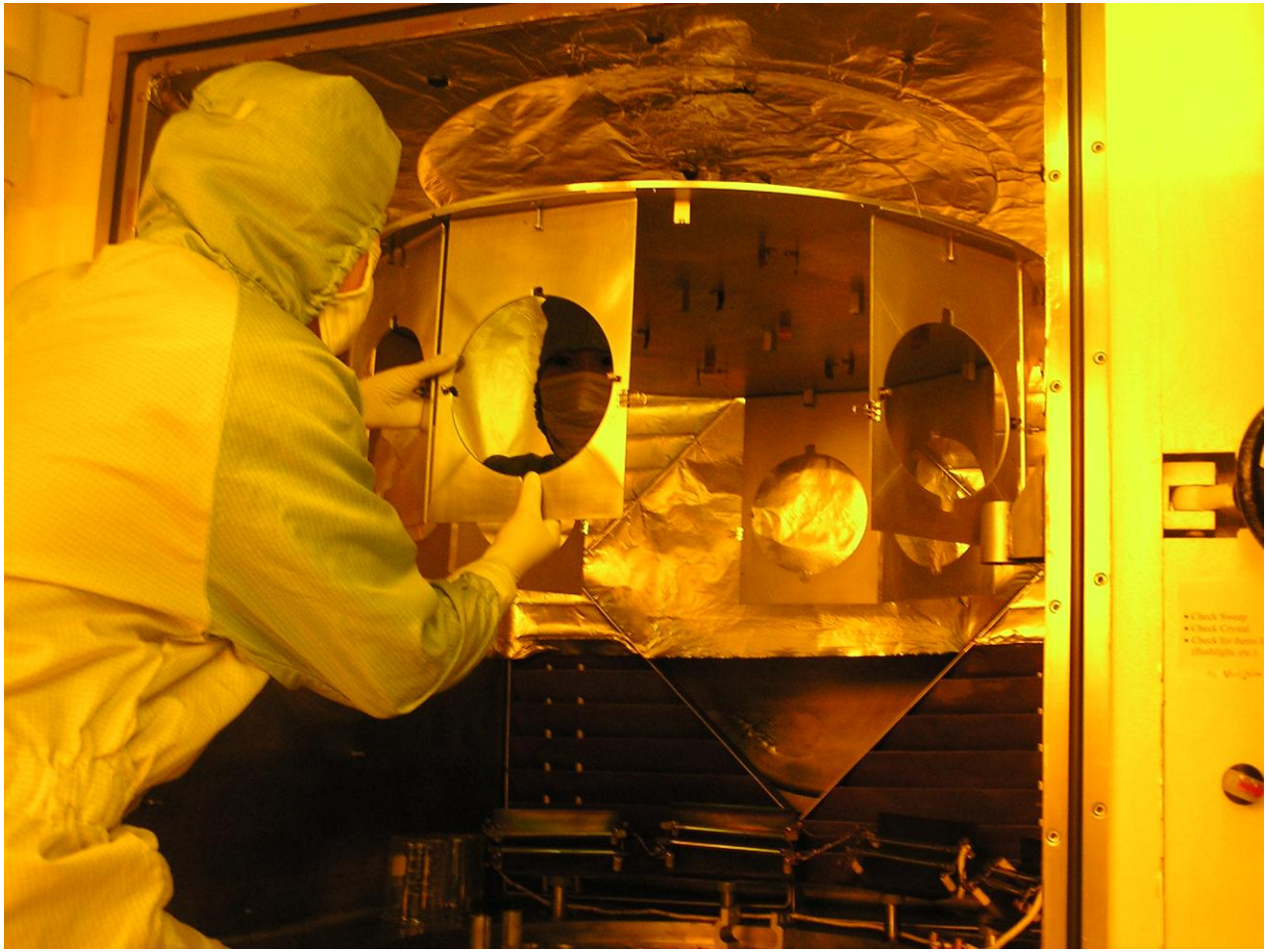
Leica Wafer Microscpoe



Coating Chamber



Coating Chamber Load/Unload



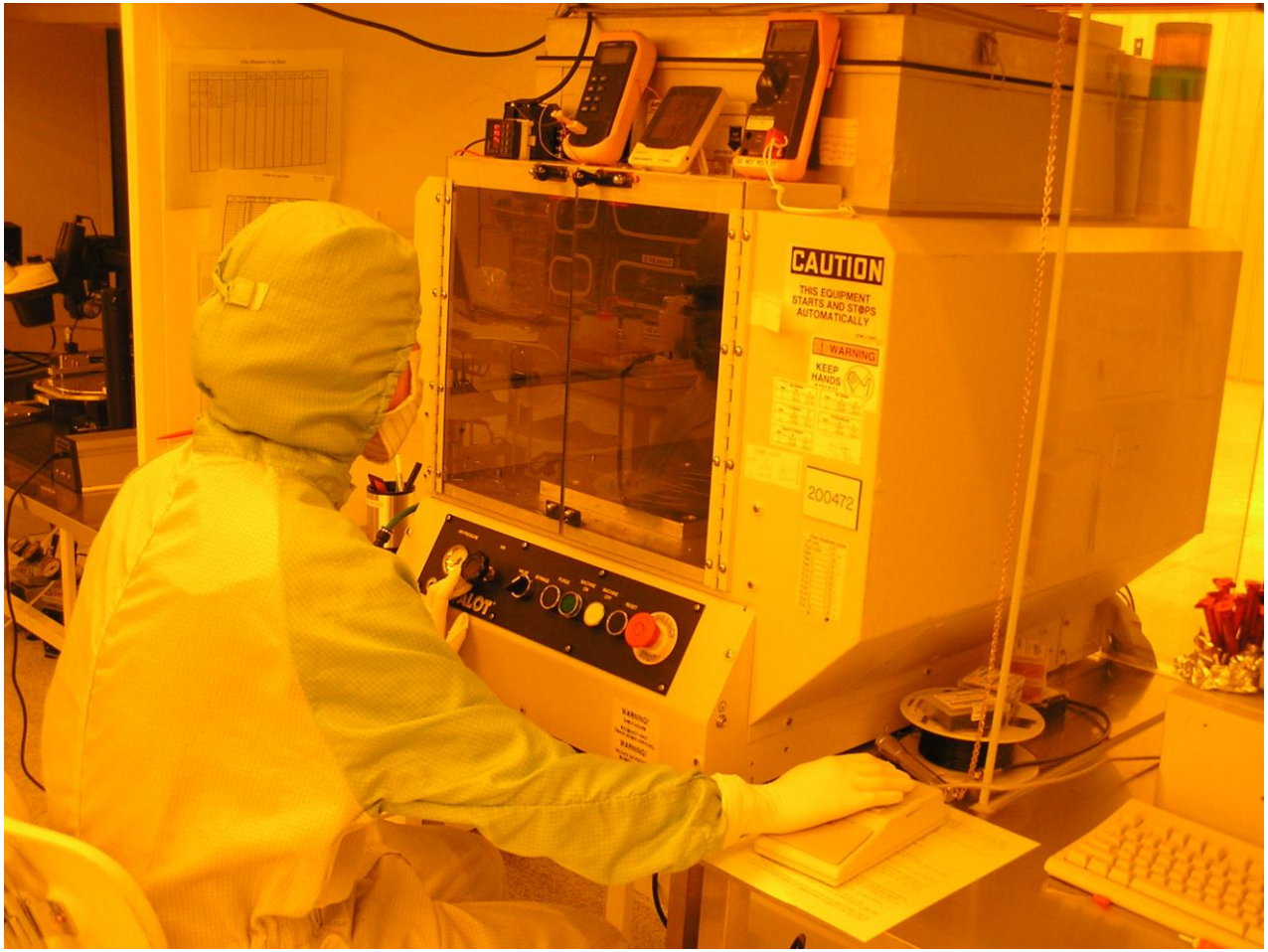
Pre-Tilt Measurement



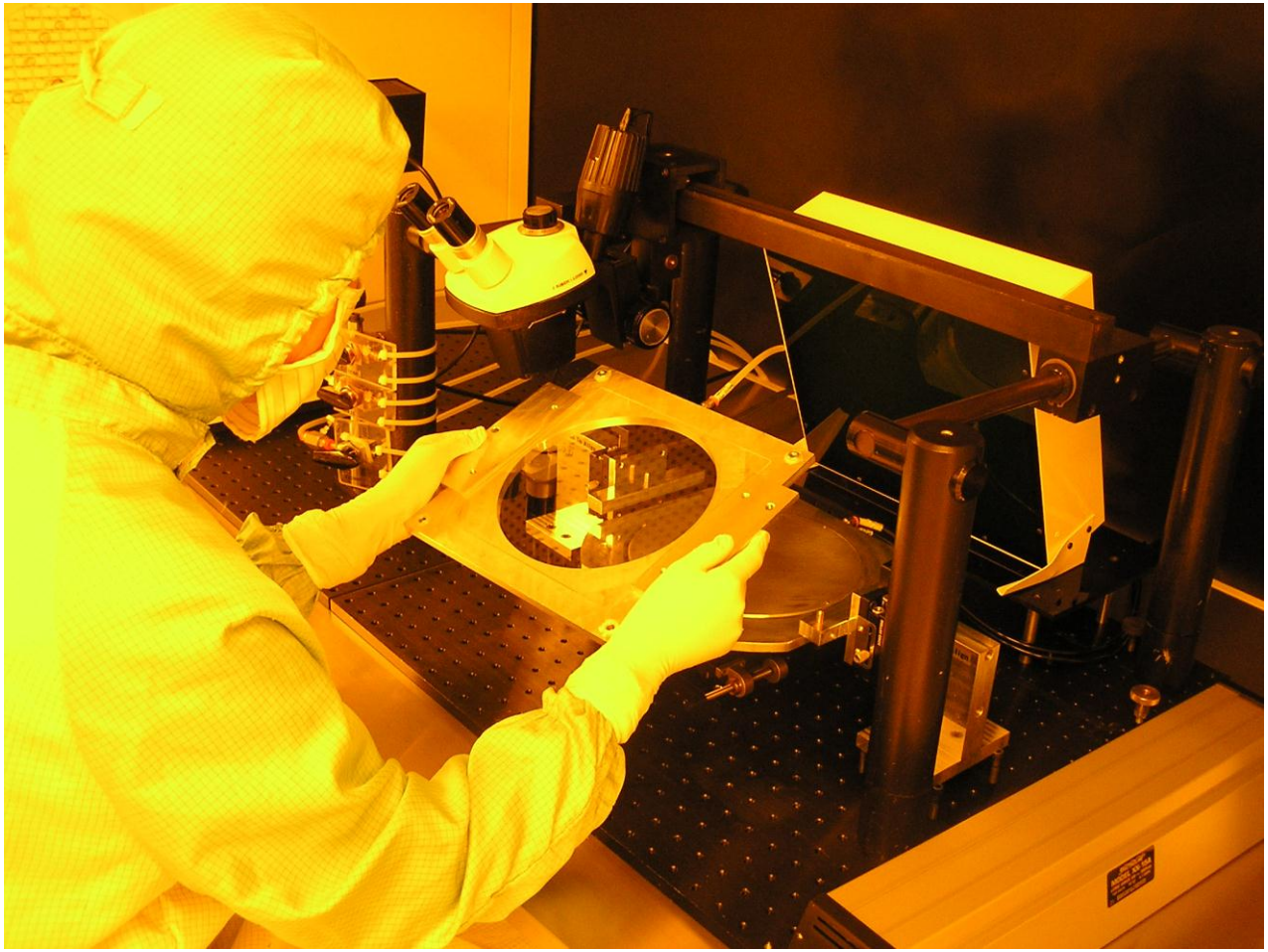
Dispense and Lamination



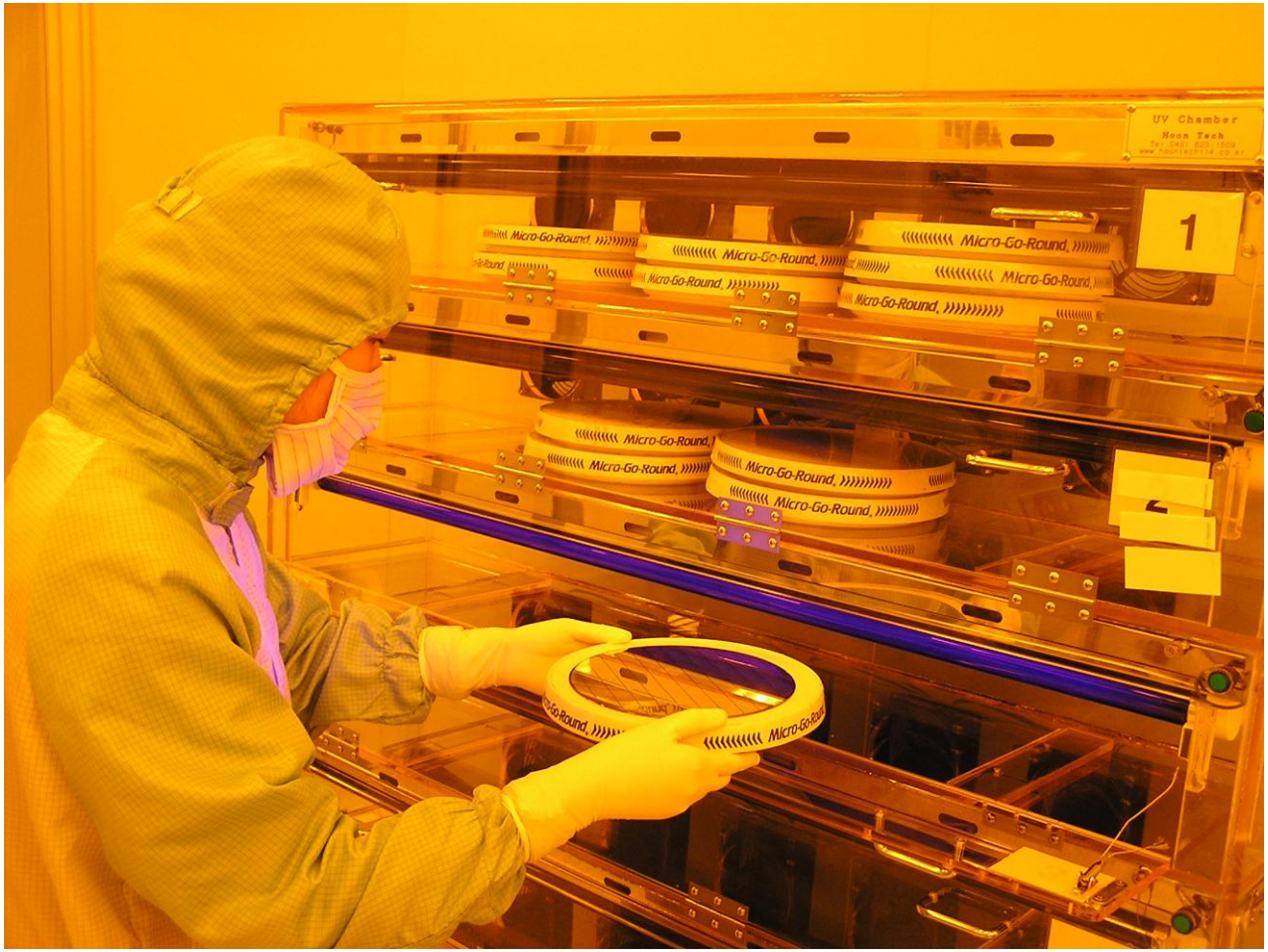
Perimeter Seal Dispense



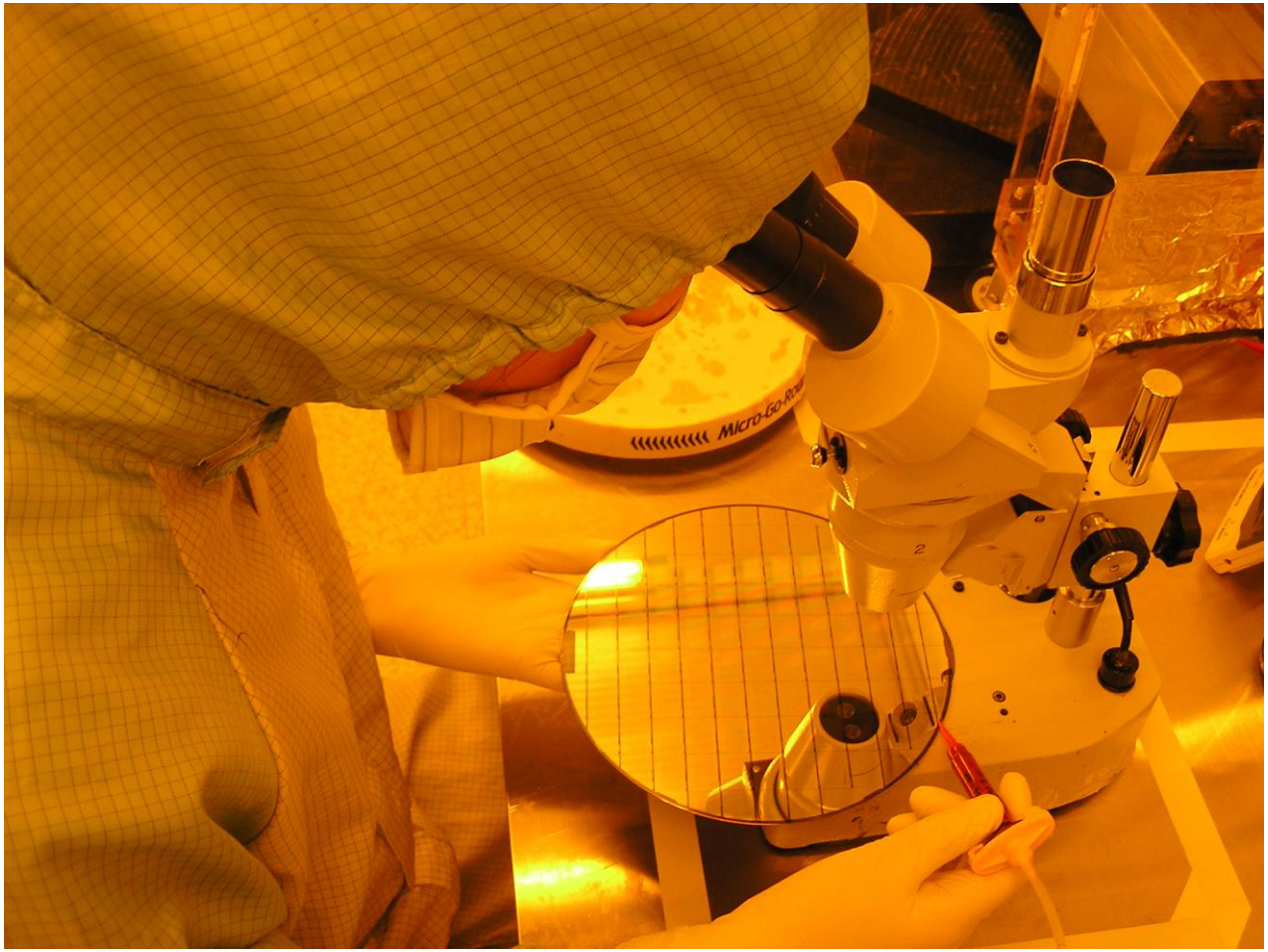
Lamination Station



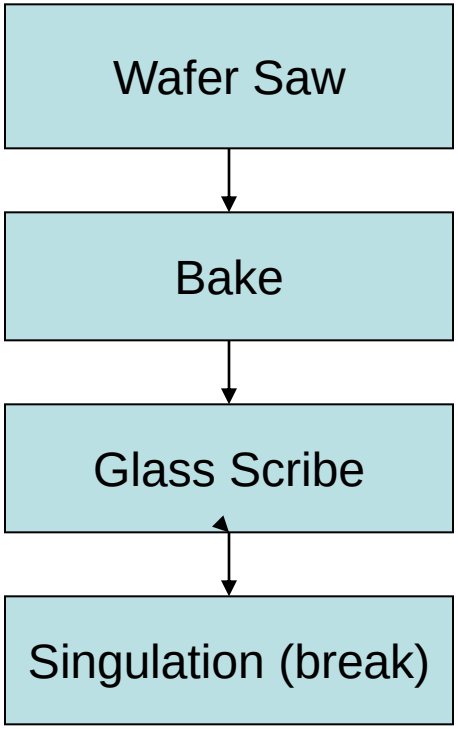
UV Curing Racks



Wafer Defect Analysis



Cell Separation



Laminate Thickness Gauging



Wafer Saws



Wafer Saw



Post Saw Bake Ovens



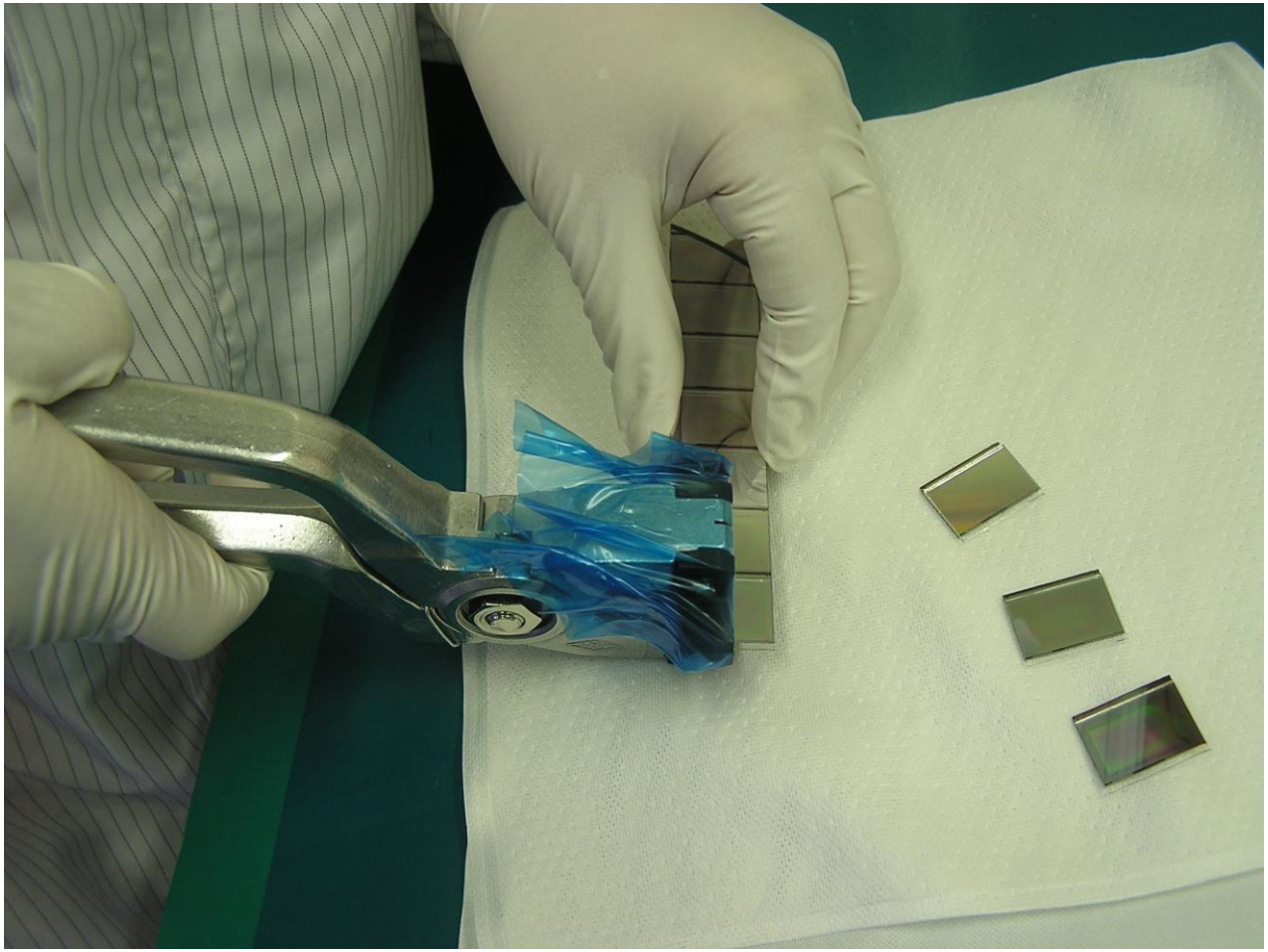
Scribe and Break



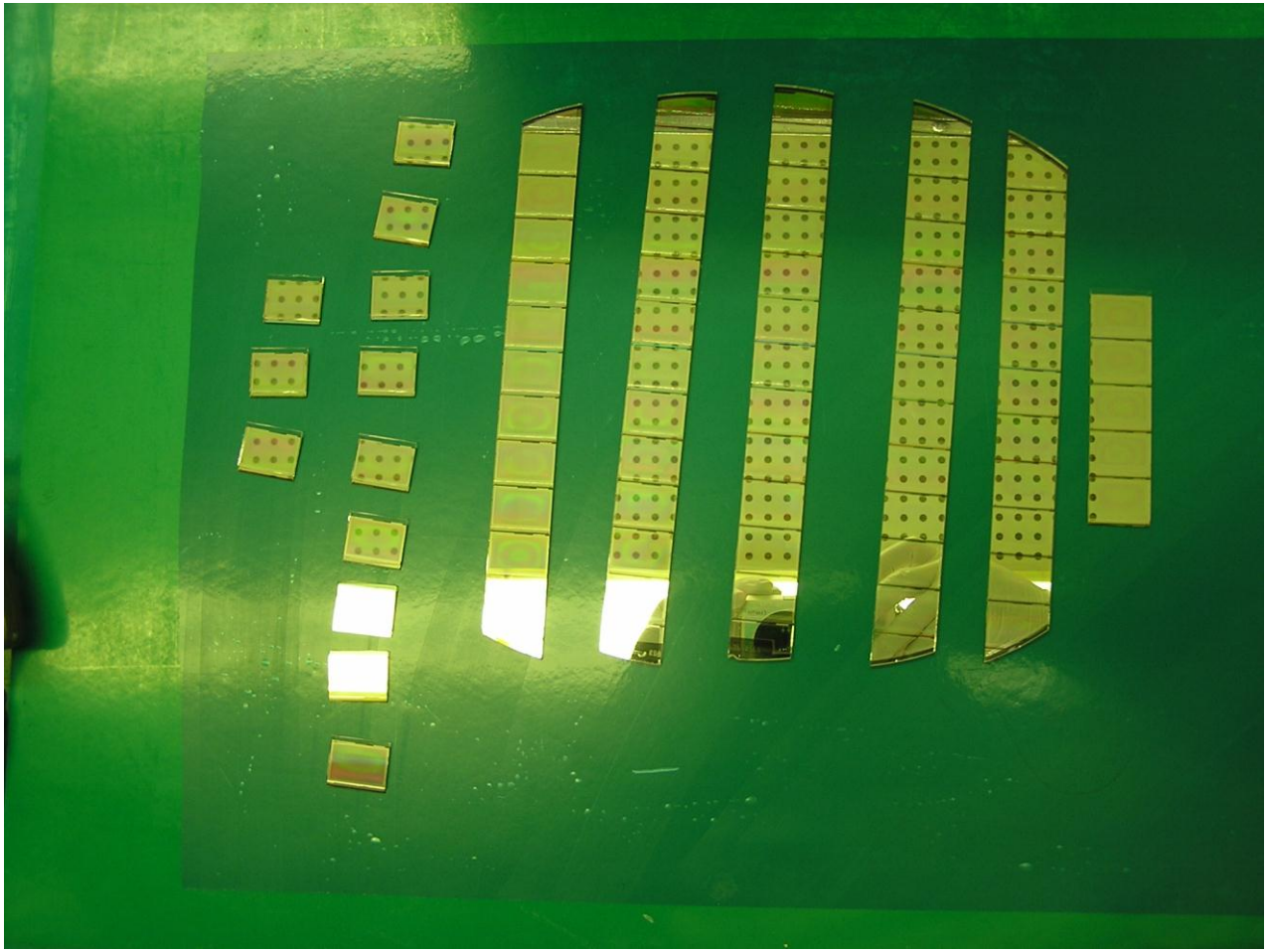
Glass Scribe



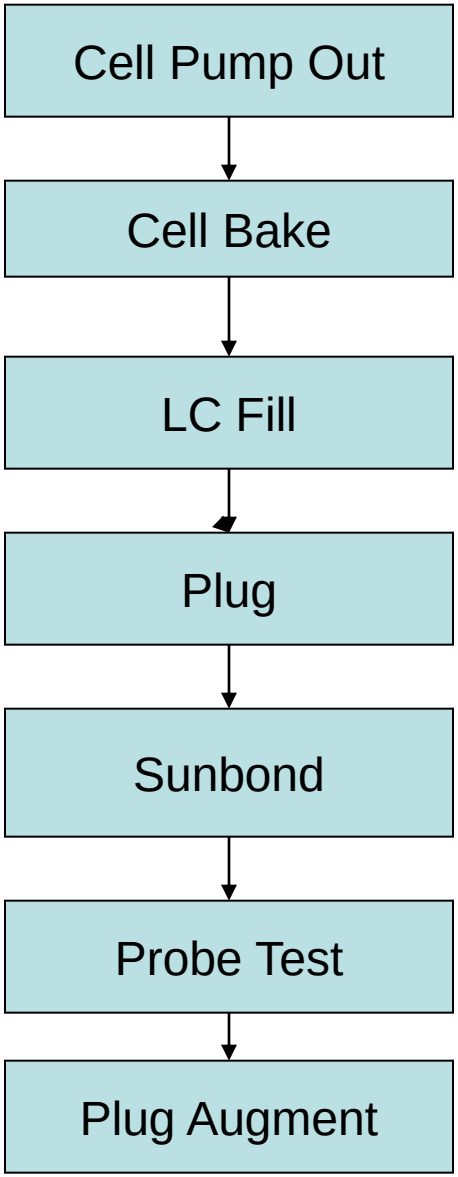
Singulation Break



Partially Singulated Wafer



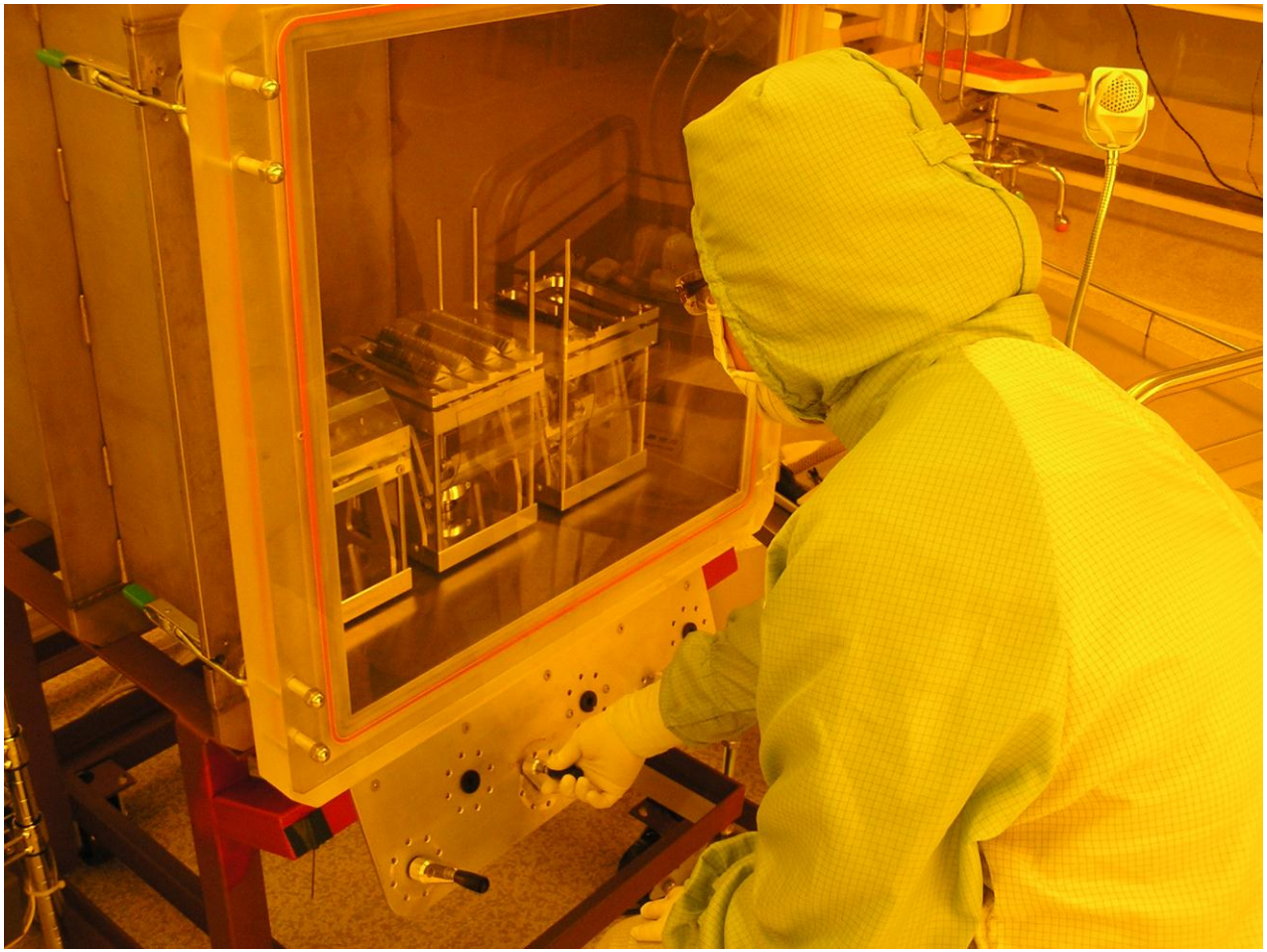
LC Fill and Plug



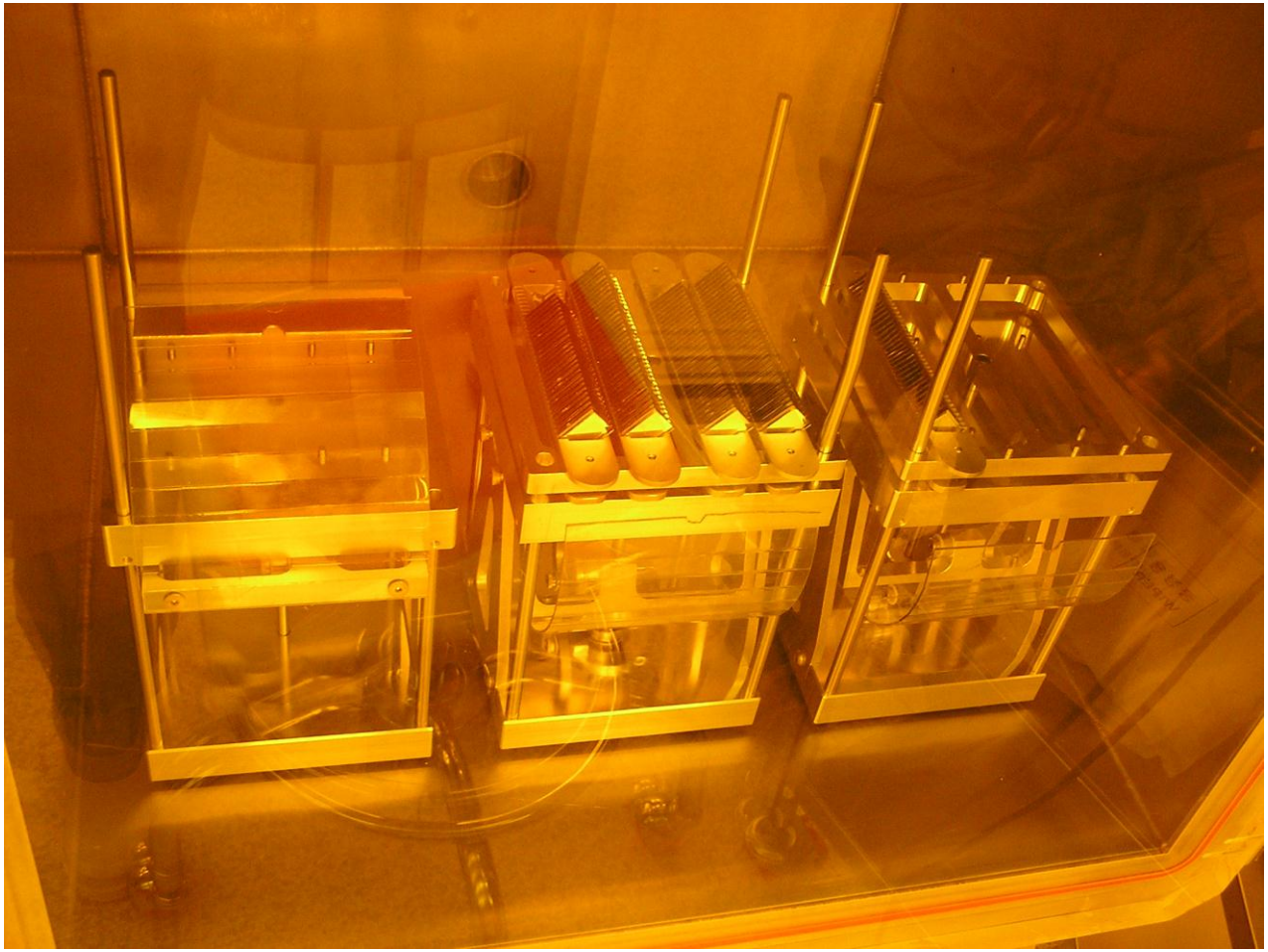
LC Fill



LC Fill Chamber



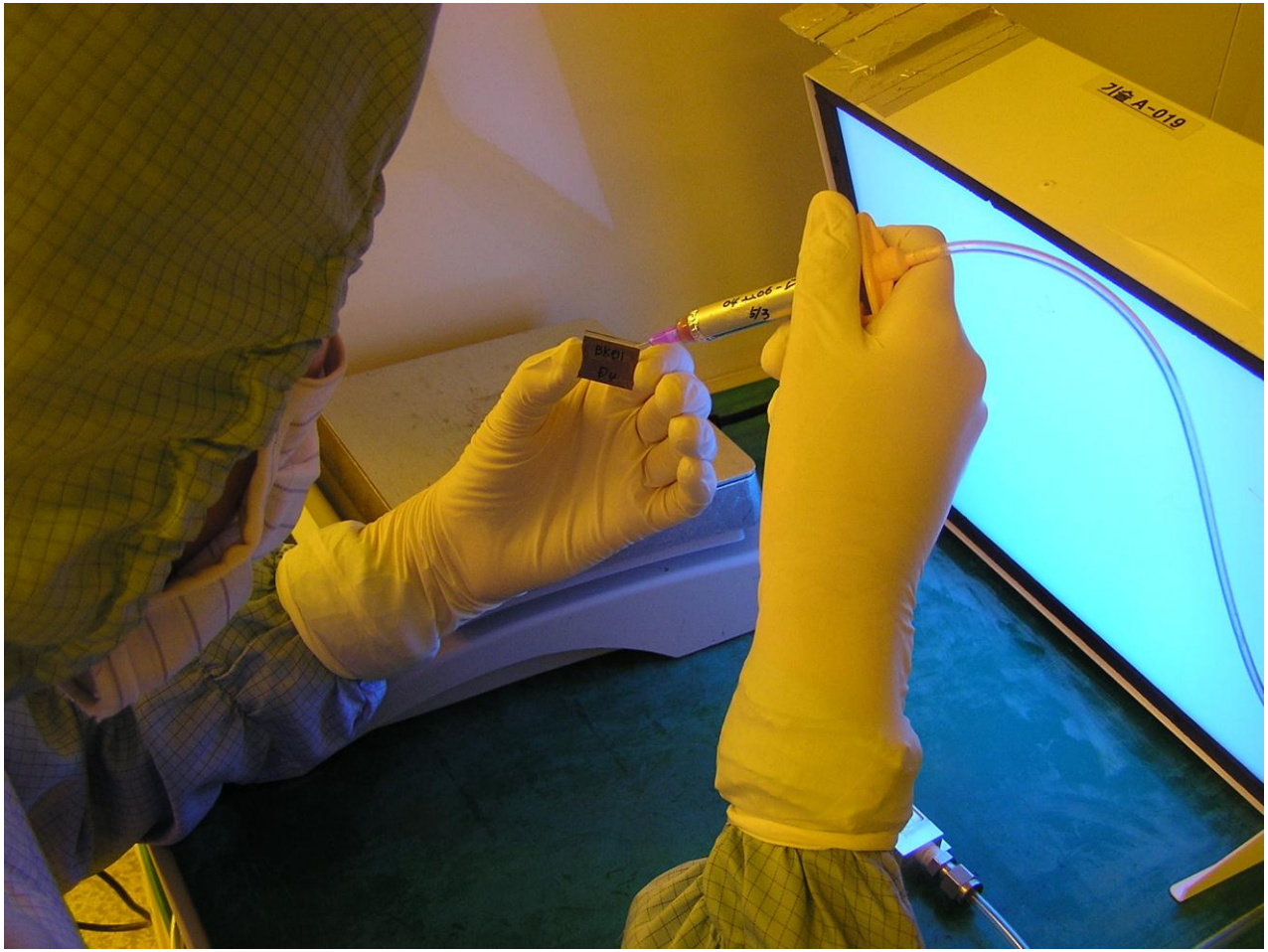
LC Fill Chamber Closeup



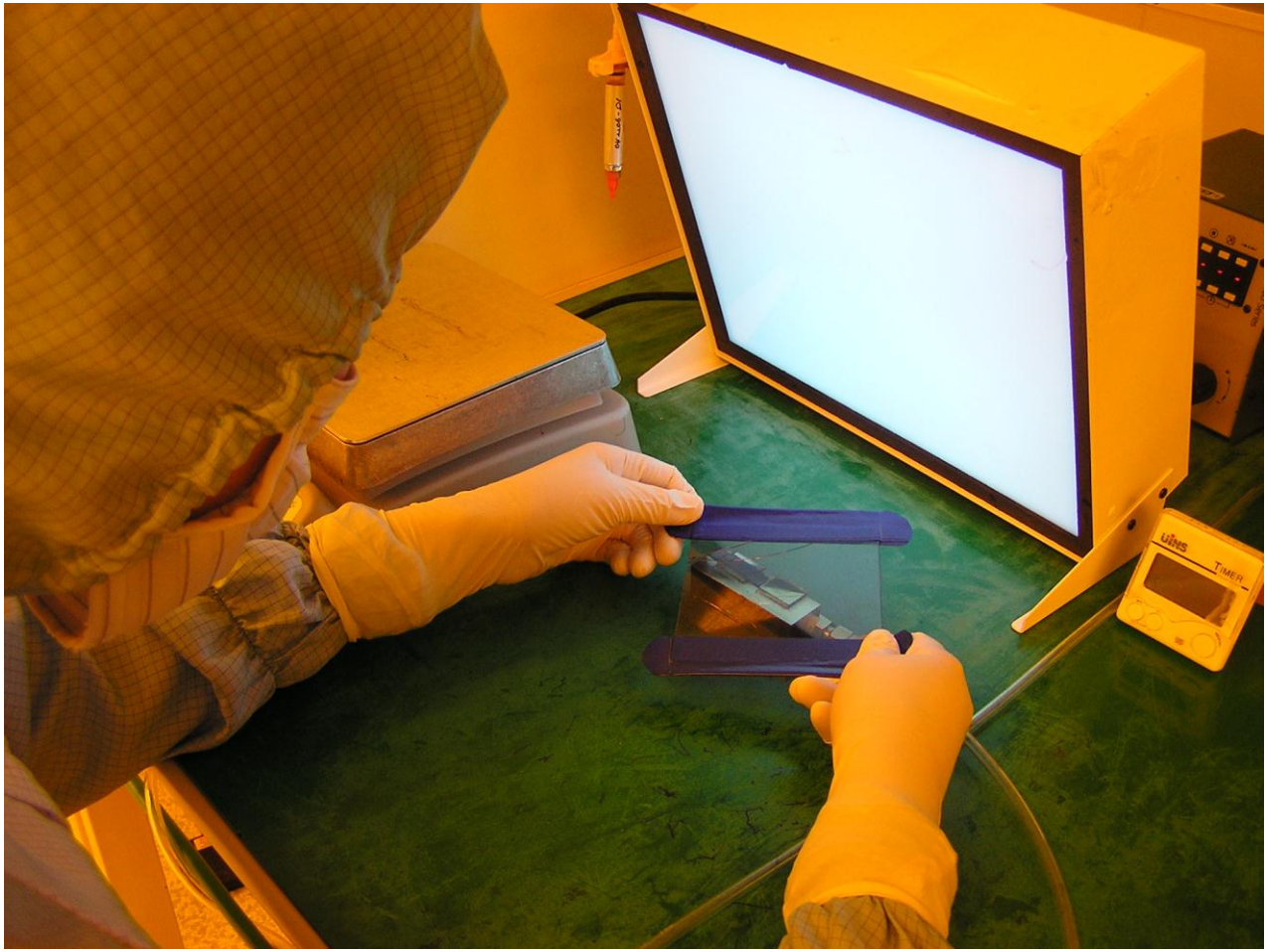
Cell Plugging



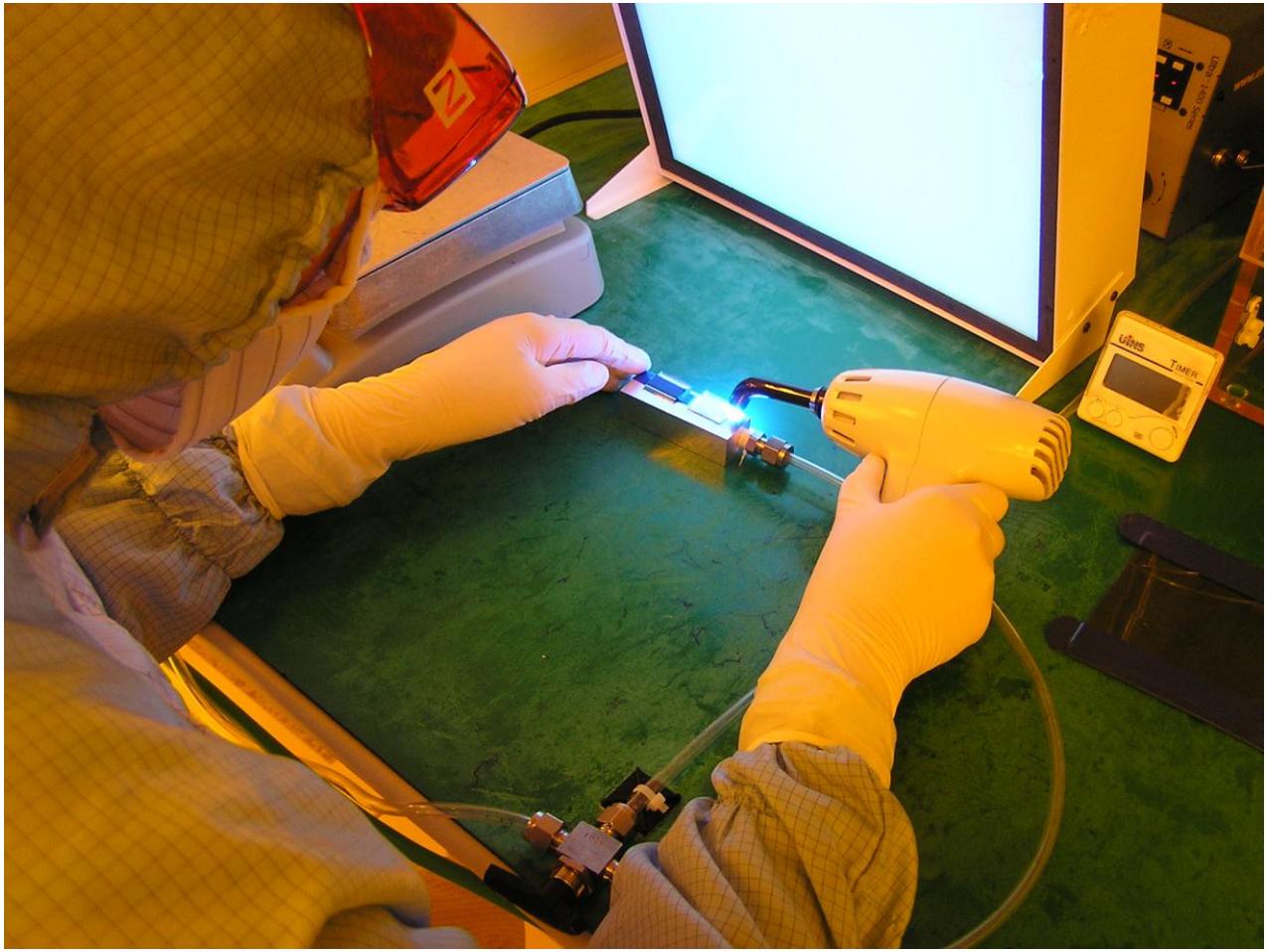
Plug Dispense



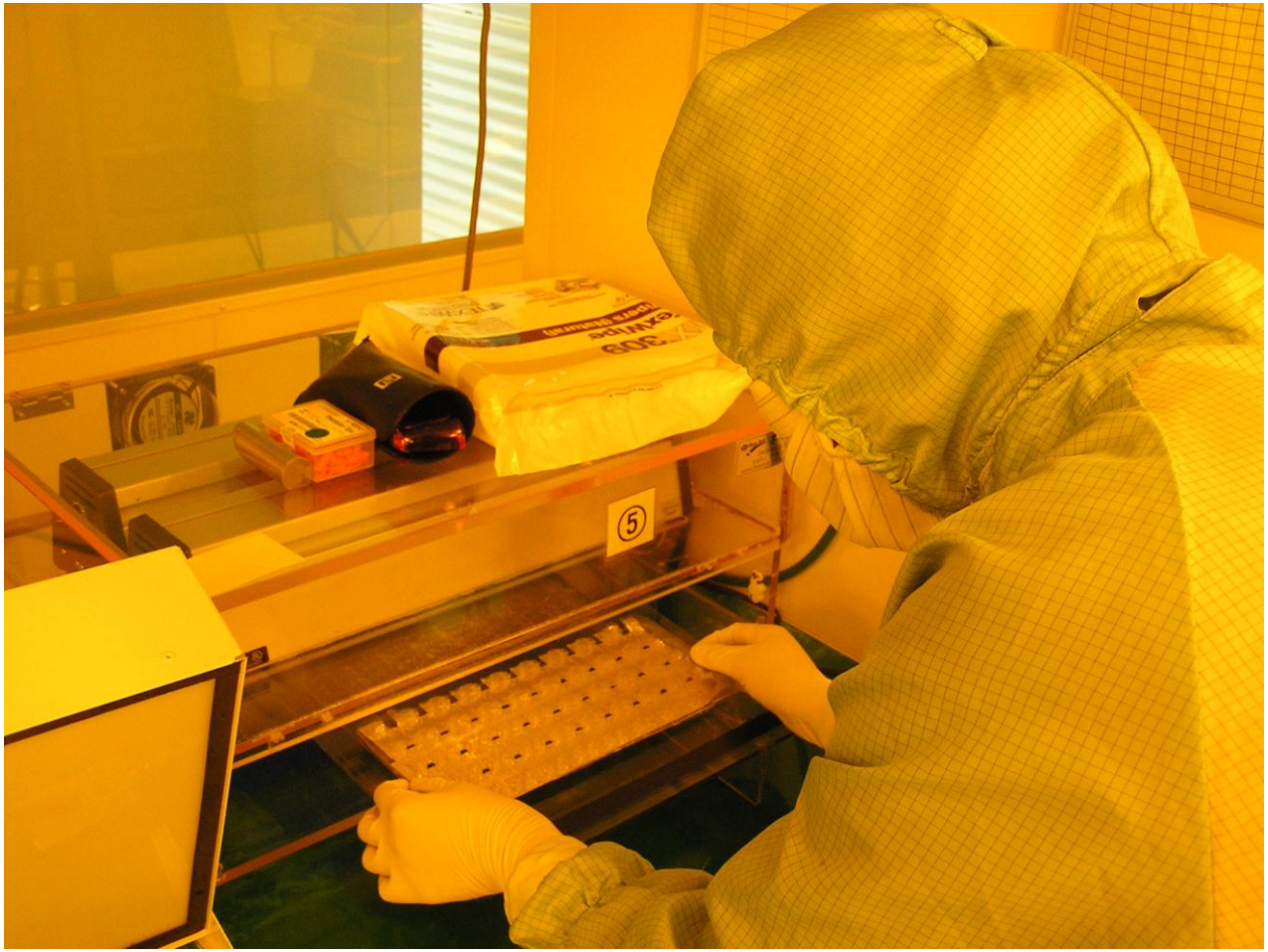
Plug Pulldown Check



Plug Spot UV Cure



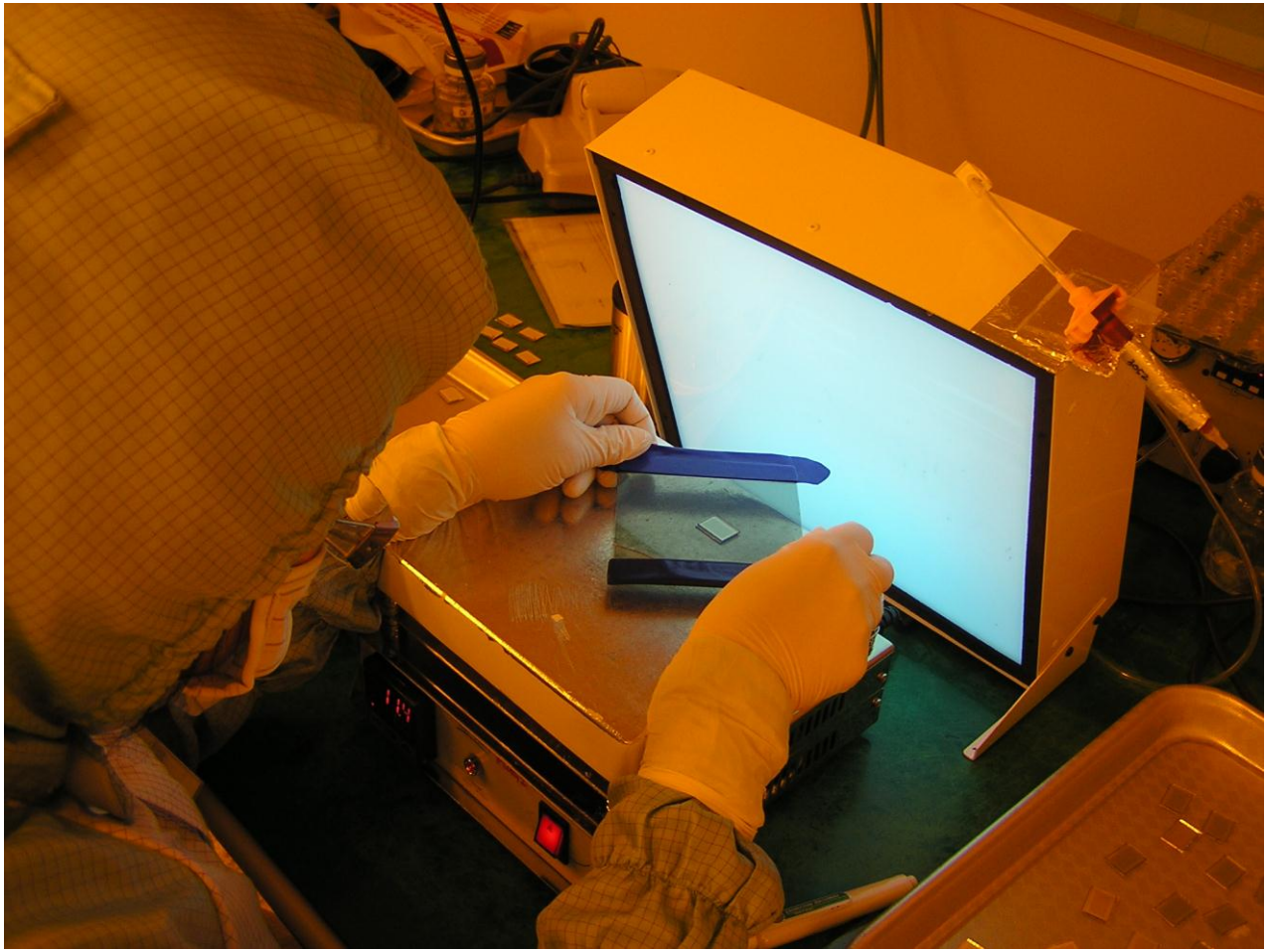
Plug UV Cure



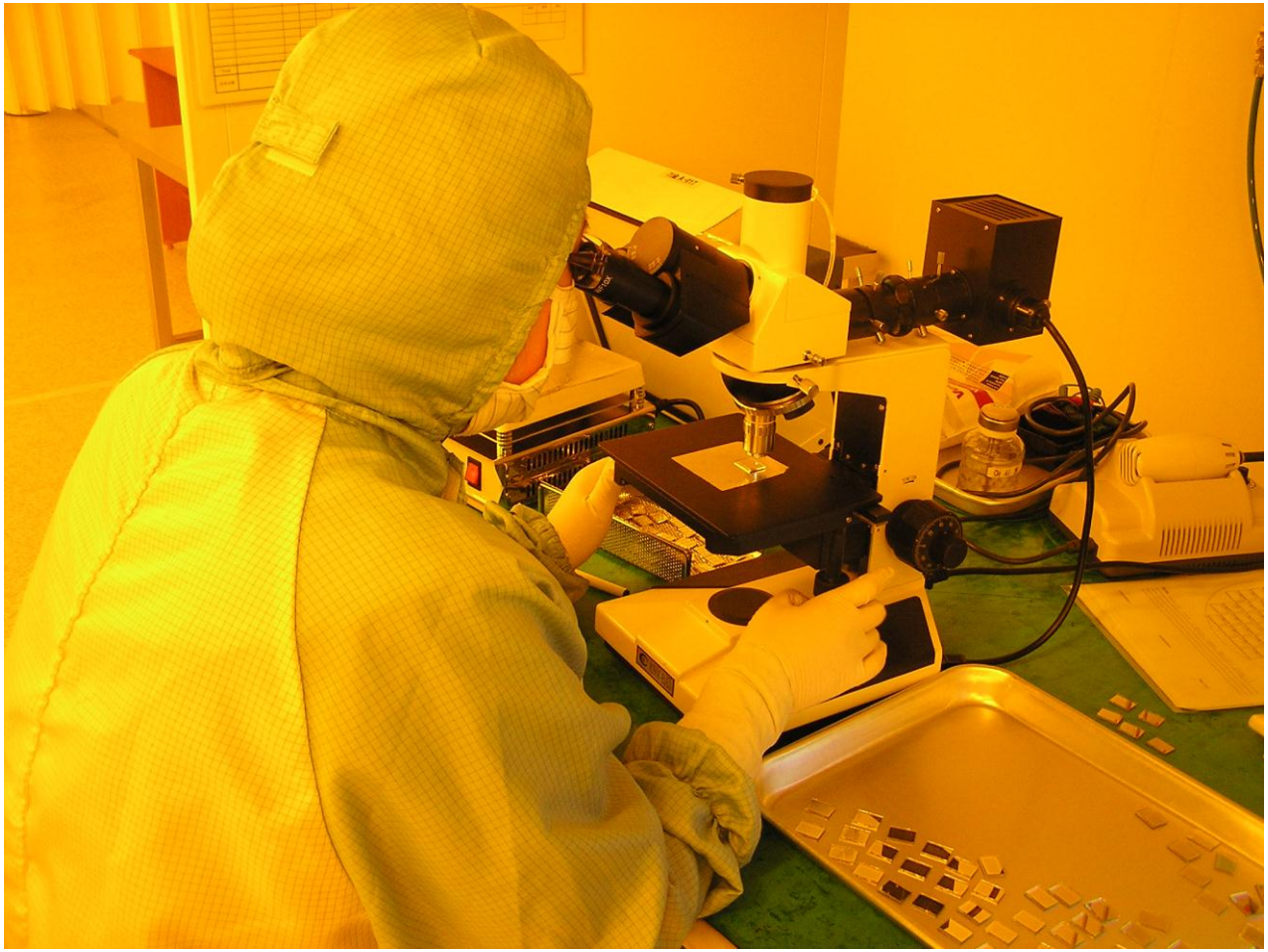
Plug Thermal Cure



Fringe Inspection



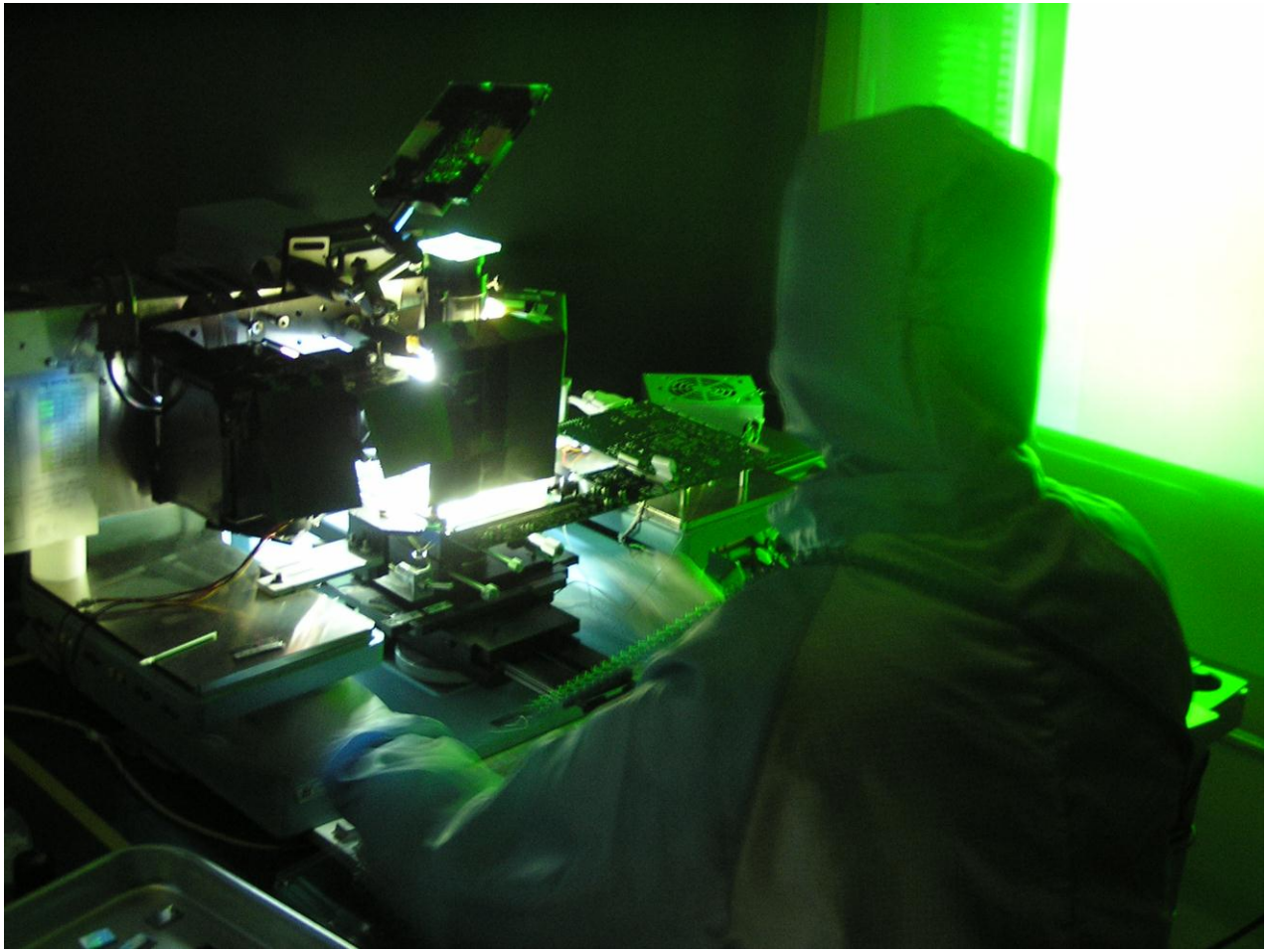
Cell Inspection



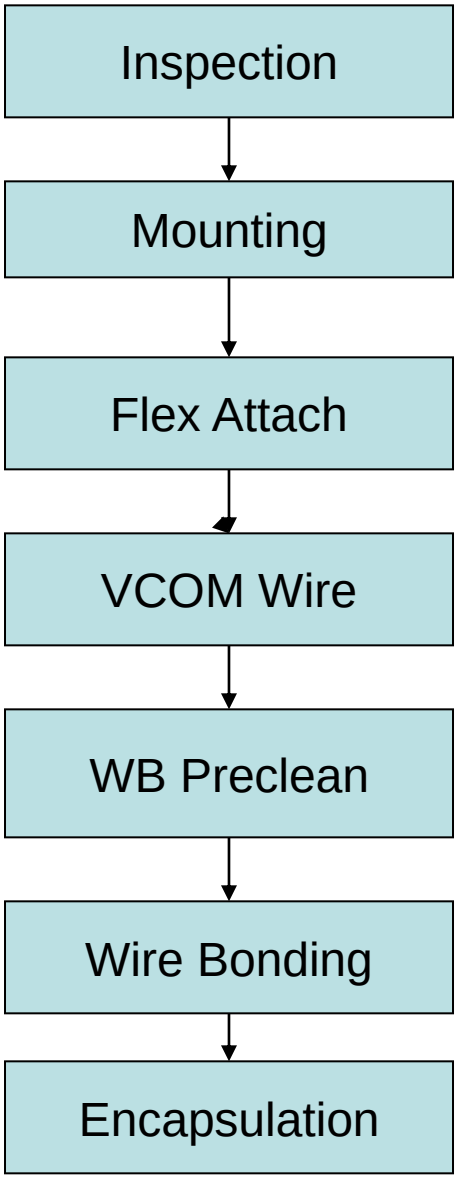
ITO Sunbond Connection



Optical Probe Testing



Imager Assembly



Mounting and Wirebonding



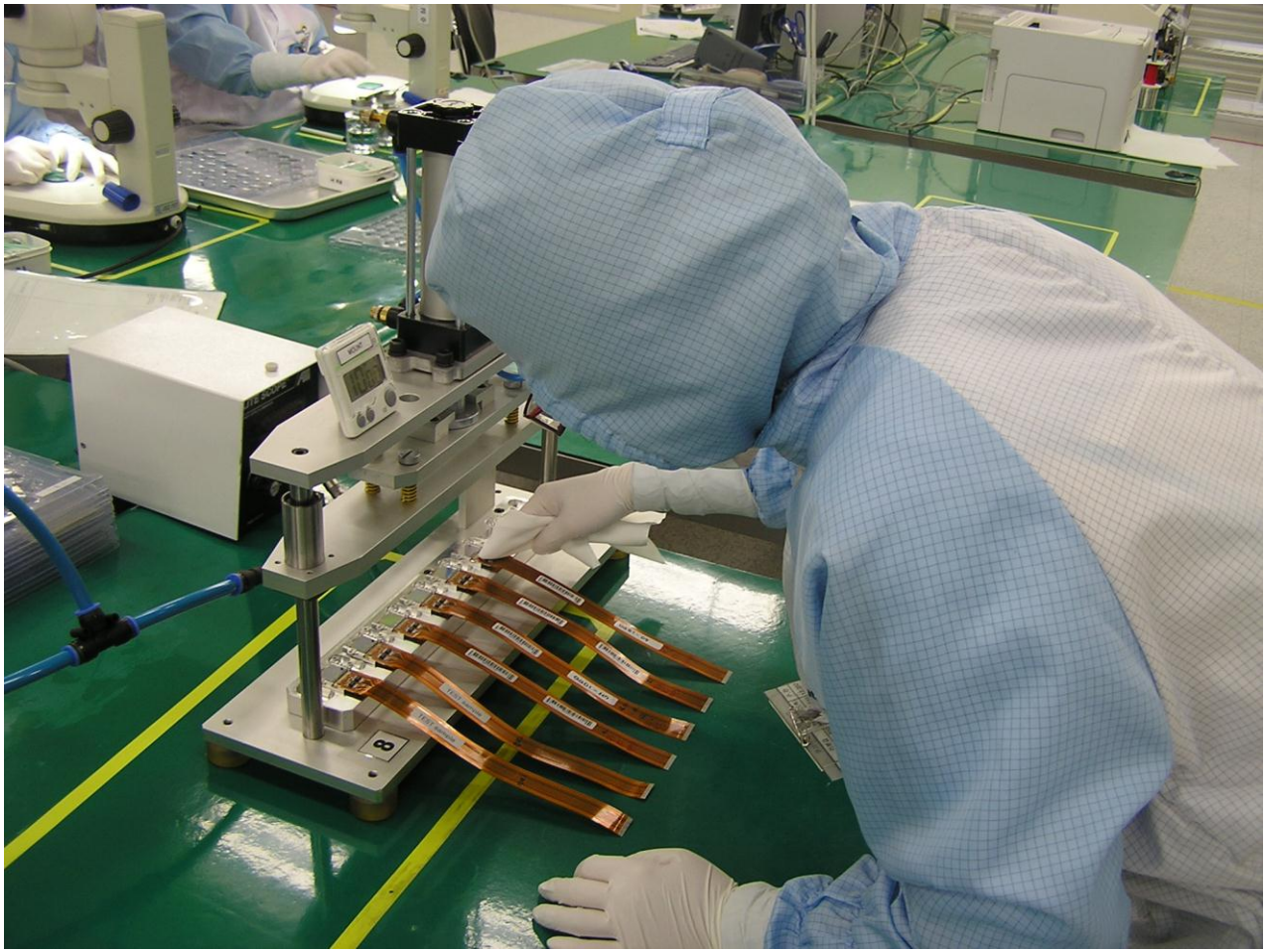
Mount Adhesive Dispense



Cell Mounting



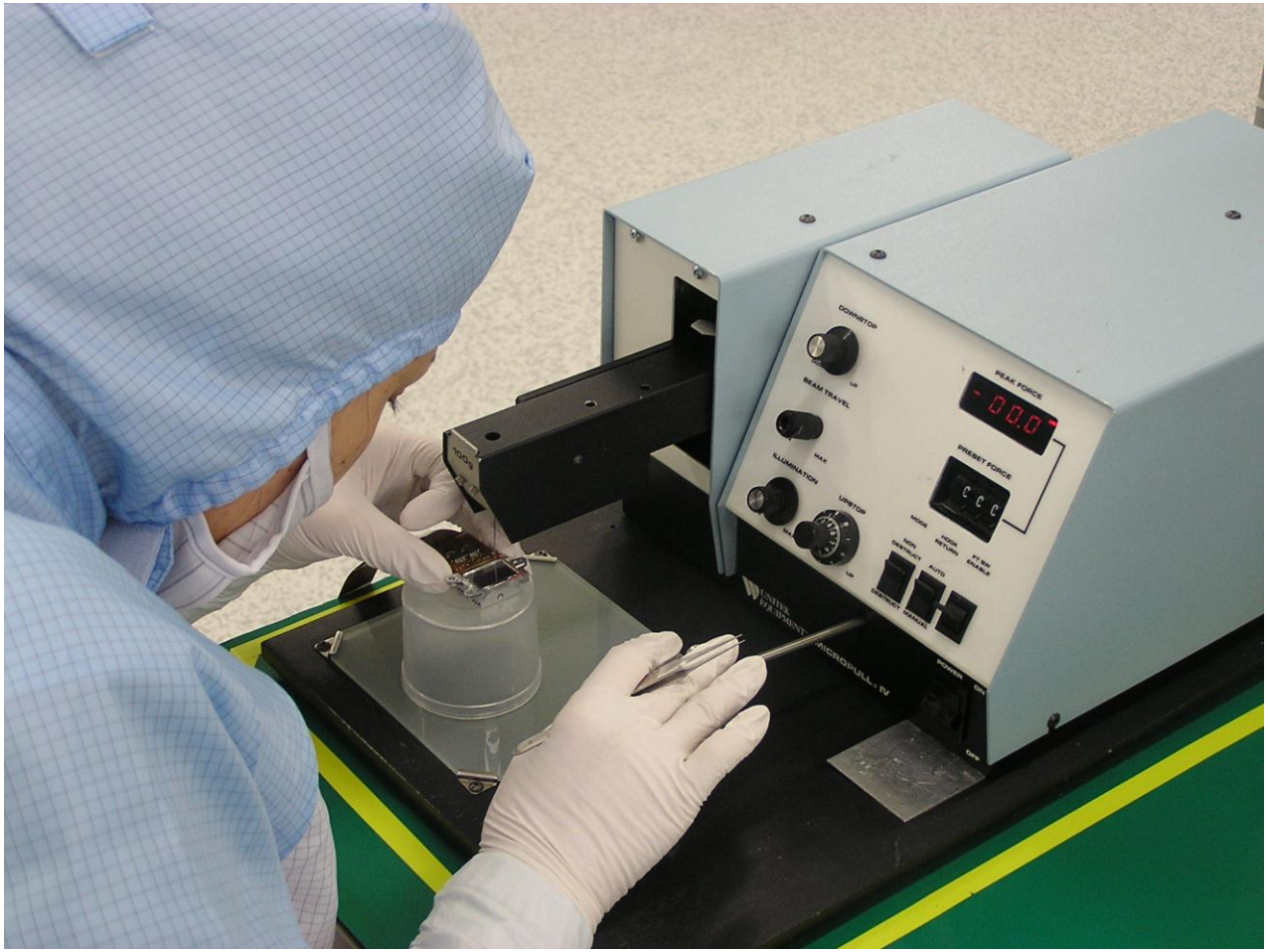
Flex Attach



Auto Wire Bonder



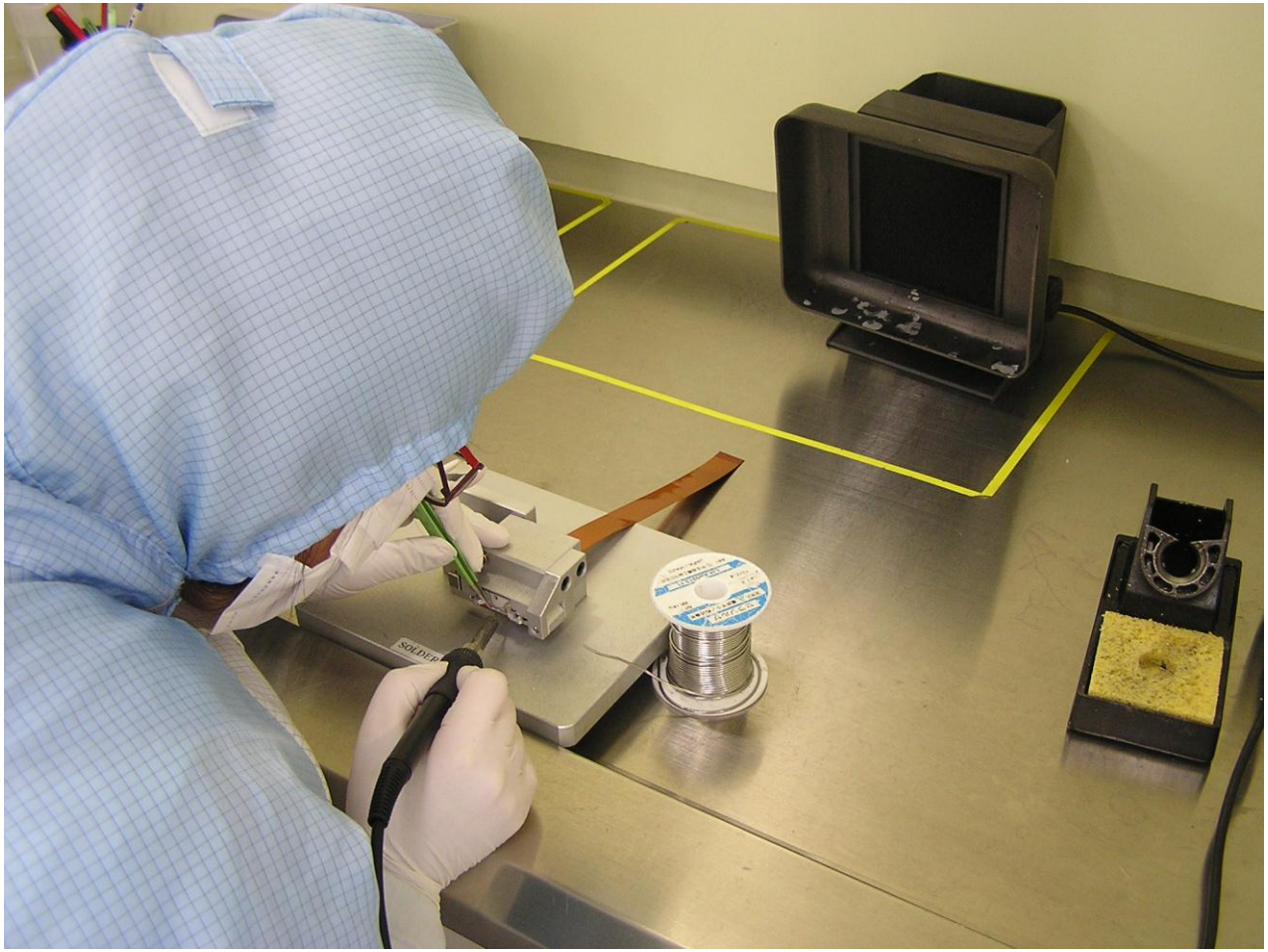
Wire Bond Pull Tester



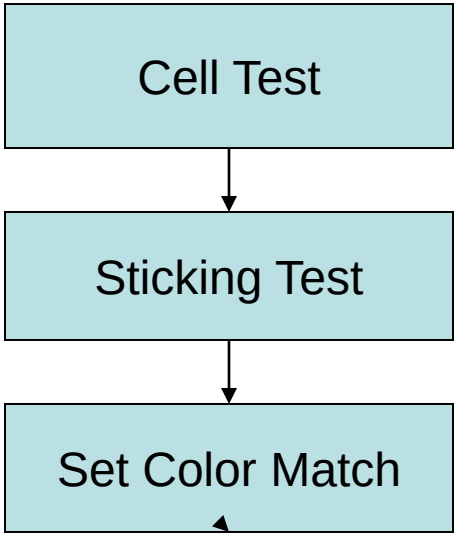
VCOM Wire Auto Stripper



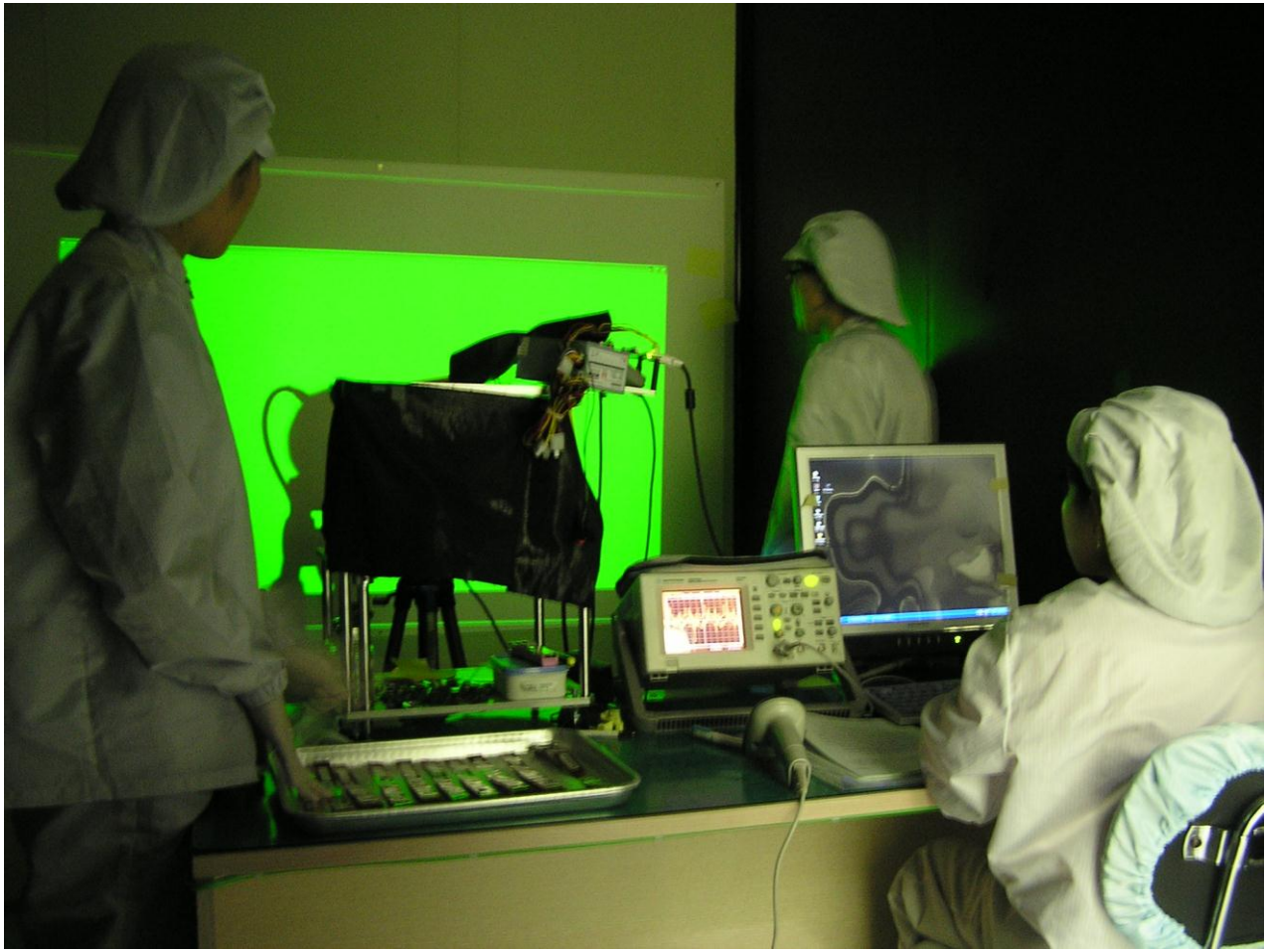
VCOM Wire Attach



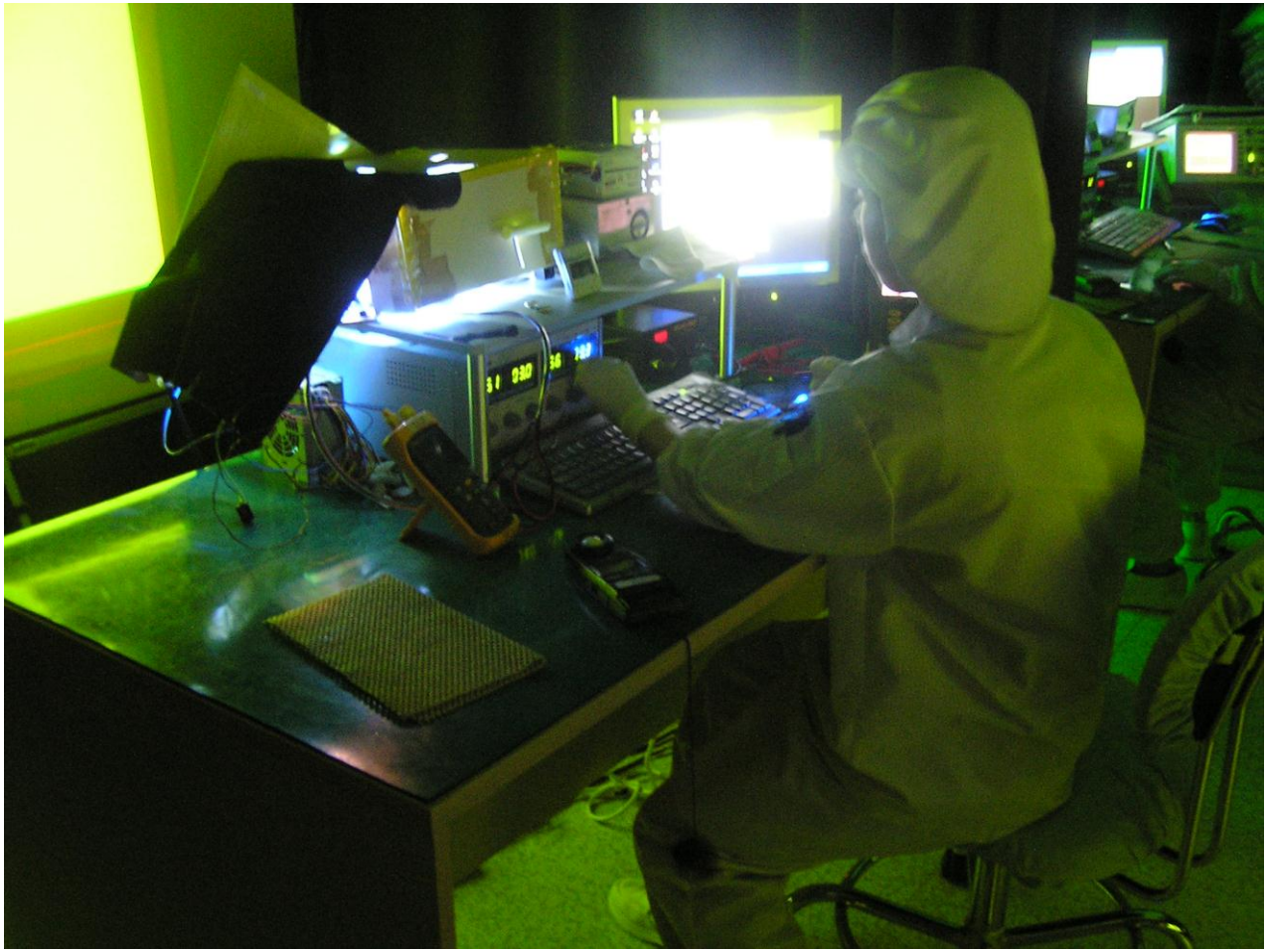
Production Test



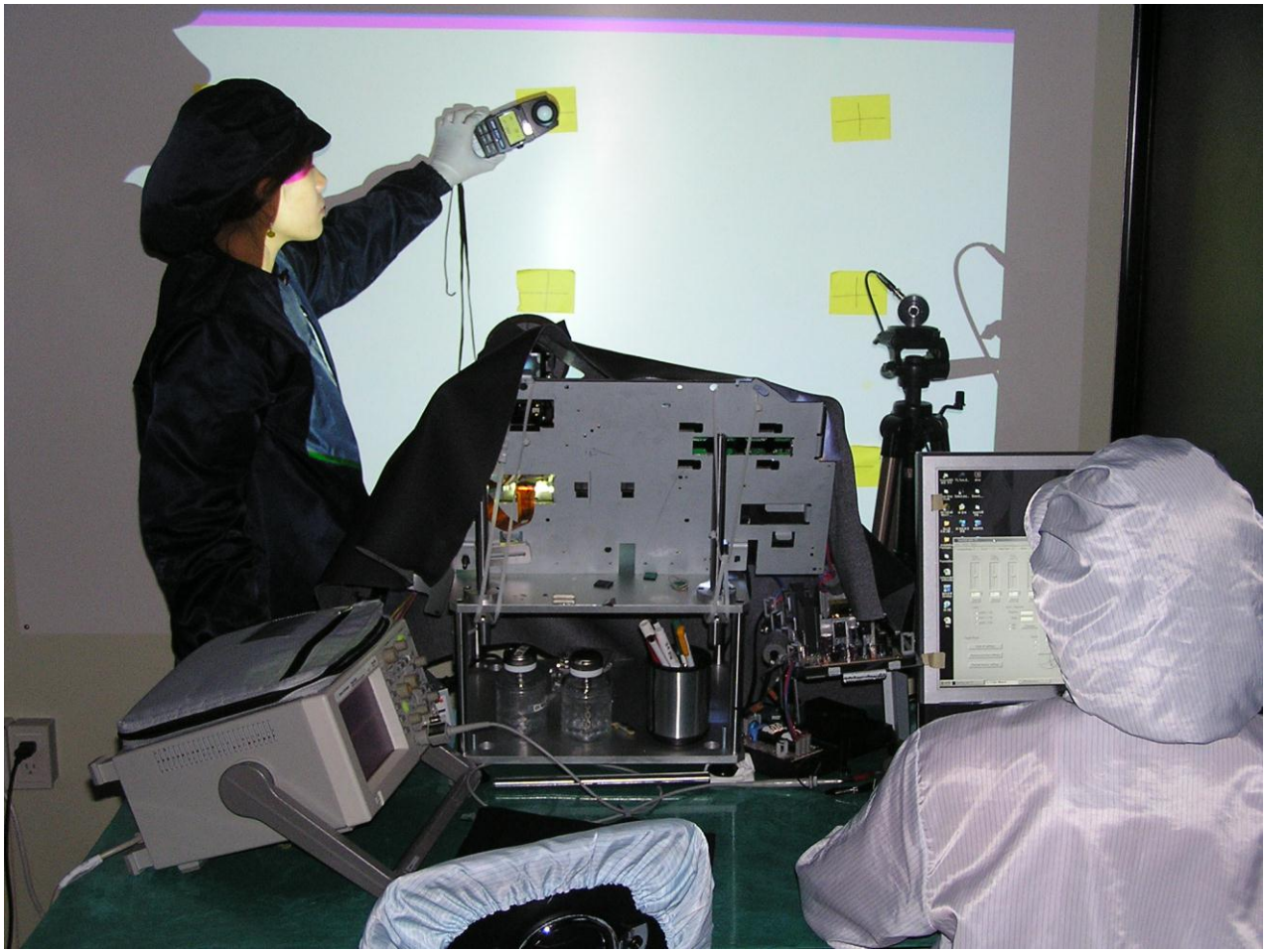
Imager Testing



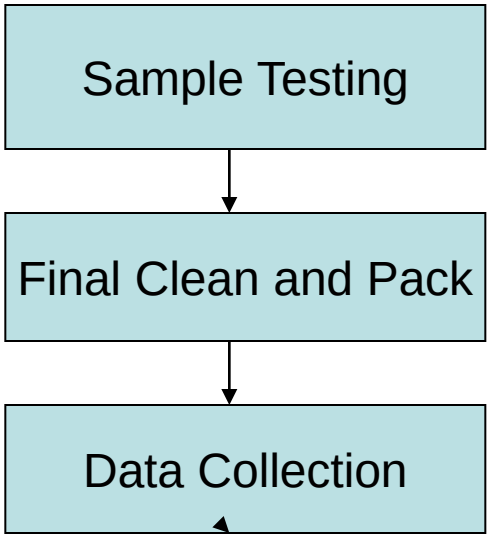
Sticking Sample Test



Color Uniformity Check



OQC/Pack&Ship



Final Clean and Pack



Vacuum Package Sealer

